

Contents

Preface

xi

1 Microelectromechanical systems (MEMS) and radio frequency

MEMS	1
1.1 Introduction	1
1.2 MEMS	2
1.3 Microfabrications for MEMS	5
1.3.1 Bulk micromachining of silicon	5
1.3.2 Surface micromachining of silicon	8
1.3.3 Wafer bonding for MEMS	9
1.3.4 LIGA process	11
1.3.5 Micromachining of polymeric MEMS devices	13
1.3.6 Three-dimensional microfabrications	15
1.4 Electromechanical transducers	16
1.4.1 Piezoelectric transducers	18
1.4.2 Electrostrictive transducers	20
1.4.3 Magnetostrictive transducers	22
1.4.4 Electrostatic actuators	24
1.4.5 Electromagnetic transducers	27
1.4.6 Electrodynamic transducers	29
1.4.7 Electrothermal actuators	32
1.4.8 Comparison of electromechanical actuation schemes	34
1.5 Microsensing for MEMS	35
1.5.1 Piezoresistive sensing	35
1.5.2 Capacitive sensing	37
1.5.3 Piezoelectric sensing	37
1.5.4 Resonant sensing	38
1.5.5 Surface acoustic wave sensors	38
1.6 Materials for MEMS	42
1.6.1 Metal and metal alloys for MEMS	42
1.6.2 Polymers for MEMS	42
1.6.3 Other materials for MEMS	44
1.7 Scope of this book	44
References	45

2 MEMS materials and fabrication techniques	51
2.1 Metals	51
2.1.1 Evaporation	51
2.1.2 Sputtering	53
2.2 Semiconductors	54
2.2.1 Electrical and chemical properties	54
2.2.2 Growth and deposition	57
2.3 Thin films for MEMS and their deposition techniques	61
2.3.1 Oxide film formation by thermal oxidation	61
2.3.2 Deposition of silicon dioxide and silicon nitride	62
2.3.3 Polysilicon film deposition	64
2.3.4 Ferroelectric thin films	64
2.4 Materials for polymer MEMS	67
2.4.1 Classification of polymers	67
2.4.2 UV radiation curing	74
2.4.3 SU-8 for polymer MEMS	80
2.5 Bulk micromachining for silicon-based MEMS	84
2.5.1 Isotropic and orientation-dependent wet etching	84
2.5.2 Dry etching	88
2.5.3 Buried oxide process	88
2.5.4 Silicon fusion bonding	89
2.5.5 Anodic bonding	90
2.6 Silicon surface micromachining	91
2.6.1 Sacrificial layer technology	91
2.6.2 Material systems in sacrificial layer technology	92
2.6.3 Surface micromachining using plasma etching	93
2.6.4 Combined integrated-circuit technology and anisotropic wet etching	94
2.7 Microstereolithography for polymer MEMS	94
2.7.1 Scanning method	95
2.7.2 Two-photon microstereolithography	96
2.7.3 Surface micromachining of polymer MEMS	97
2.7.4 Projection method	97
2.7.5 Polymeric MEMS architecture with silicon, metal and ceramics	102
2.7.6 Microstereolithography integrated with thick-film lithography	105
2.8 Conclusions	105
References	105
3 RF MEMS switches and micro relays	109
3.1 Introduction	109
3.2 Switch parameters	111
3.3 Basics of switching	115
3.3.1 Mechanical switches	116
3.3.2 Electronic switches	117

3.4	Switches for RF and microwave applications	117
3.4.1	Mechanical RF switches	118
3.4.2	PIN diode RF switches	119
3.4.3	Metal oxide semiconductor field effect transistors and monolithic microwave integrated circuits	123
3.4.4	RF MEMS switches	124
3.4.5	Integration and biasing issues for RF switches	125
3.5	Actuation mechanisms for MEMS devices	127
3.5.1	Electrostatic switching	128
3.5.2	Approaches for low-actuation-voltage switches	141
3.5.3	Mercury contact switches	146
3.5.4	Magnetic switching	148
3.5.5	Electromagnetic switching	148
3.5.6	Thermal switching	151
3.6	Bistable micro relays and microactuators	152
3.6.1	Magnetic actuation in micro relays	152
3.6.2	Relay contact force and materials	156
3.7	Dynamics of the switch operation	157
3.7.1	Switching time and dynamic response	158
3.7.2	Threshold voltage	160
3.8	MEMS switch design, modeling and evaluation	162
3.8.1	Electromechanical finite element analysis	163
3.8.2	RF design	165
3.9	MEMS switch design considerations	174
3.10	Conclusions	175
	References	178
4	MEMS inductors and capacitors	183
4.1	Introduction	183
4.2	MEMS/micromachined passive elements: pros and cons	184
4.3	MEMS inductors	184
4.3.1	Self-inductance and mutual inductance	185
4.3.2	Micromachined inductors	188
4.3.3	Effect of inductor layout	194
4.3.4	Reduction of stray capacitance of planar inductors	198
4.3.5	Approaches for improving the quality factor	200
4.3.6	Folded inductors	211
4.3.7	Modeling and design issues of planar inductors	212
4.3.8	Variable inductors	215
4.3.9	Polymer-based inductors	215
4.4	MEMS capacitors	215
4.4.1	MEMS gap-tuning capacitors	217
4.4.2	MEMS area-tuning capacitors	224
4.4.3	Dielectric tunable capacitors	228
4.5	Conclusions	229
	References	235

5 Micromachined RF filters	241
5.1 Introduction	241
5.2 Modeling of mechanical filters	244
5.2.1 Modeling of resonators	244
5.2.2 Mechanical coupling components	251
5.2.3 General considerations for mechanical filters	257
5.3 Micromechanical filters	258
5.3.1 Electrostatic comb drive	258
5.3.2 Micromechanical filters using comb drives	260
5.3.3 Micromechanical filters using electrostatic coupled beam structures	265
5.4 Surface acoustic wave filters	268
5.4.1 Basics of surface acoustic wave filter operation	269
5.4.2 Wave propagation in piezoelectric substrates	270
5.4.3 Design of interdigital transducers	271
5.4.4 Single-phase unidirectional transducers	274
5.4.5 Surface acoustic wave devices: capabilities, limitations and applications	275
5.5 Bulk acoustic wave filters	276
5.6 Micromachined filters for millimeter wave frequencies	278
5.7 Summary	282
References	283
6 Micromachined phase shifters	285
6.1 Introduction	285
6.2 Types of phase shifters and their limitations	286
6.2.1 Ferrite phase shifters	287
6.2.2 Semiconductor phase shifters	287
6.2.3 Ferroelectric thin-film phase shifters	288
6.2.4 Limitations of phase shifters	288
6.3 MEMS phase shifters	289
6.3.1 Switched delay line phase shifters	289
6.3.2 Distributed MEMS phase shifters	289
6.3.3 Polymer-based phase shifters	296
6.4 Ferroelectric phase shifters	298
6.4.1 Distributed parallel plate capacitors	299
6.4.2 Bilateral interdigital phase shifters	301
6.4.3 Interdigital capacitor phase shifters	304
6.5 Applications	305
6.6 Conclusions	305
References	306
7 Micromachined transmission lines and components	309
7.1 Introduction	309
7.2 Micromachined transmission lines	310
7.2.1 Losses in transmission lines	311
7.2.2 Co-planar transmission lines	313

7.2.3	Microshield and membrane-supported transmission lines	316
7.2.4	Microshield circuit components	321
7.2.5	Micromachined waveguide components	324
7.2.6	Micromachined directional couplers	327
7.2.7	Micromachined mixer	327
7.2.8	Passive components: resonators and filters	330
7.2.9	Micromachined antennae	332
7.3	Design, fabrication and measurement	334
7.3.1	Design	335
7.3.2	Fabrication	335
7.3.3	Evaluation	335
7.4	Conclusions	337
	References	338
8	Micromachined antennae	343
8.1	Introduction	343
8.2	Overview of microstrip antennae	344
8.2.1	Basic characteristics of microstrip antennae	344
8.2.2	Design parameters of microstrip antennae	347
8.3	Micromachining techniques to improve antenna performance	351
8.4	Micromachining as a fabrication process for small antennae	356
8.5	Micromachined reconfigurable antennae	360
8.6	Summary	362
	References	363
9	Integration and packaging for RF MEMS devices	365
9.1	Introduction	365
9.2	Role of MEMS packages	366
9.2.1	Mechanical support	366
9.2.2	Electrical interface	367
9.2.3	Protection from the environment	367
9.2.4	Thermal considerations	367
9.3	Types of MEMS packages	367
9.3.1	Metal packages	368
9.3.2	Ceramic packages	368
9.3.3	Plastic packages	368
9.3.4	Multilayer packages	369
9.3.5	Embedded overlay	369
9.3.6	Wafer-level packaging	370
9.3.7	Microshielding and self-packaging	372
9.4	Flip-chip assembly	373
9.5	Multichip module packaging	375
9.5.1	Wafer bonding	377
9.6	RF MEMS packaging: reliability issues	380
9.6.1	Packaging materials	380
9.6.2	Integration of MEMS devices with microelectronics	380

x CONTENTS

9.6.3 Wiring and interconnections	382
9.6.4 Reliability and key failure mechanisms	382
9.7 Thermal issues	383
9.8 Conclusions	383
References	384
Index	387